L Number	Hits	Search Text	DB	Time stamp
-	4	(("4340462") or ("5262029") or ("5437757") or ("5656122") or	USPAT;	2002/03/28 09:36
-	_	("61566276")).PN.	US-PGPUB USPAT;	2002/03/26 10:58
•	5	(("4340462") or ("5262029") or ("5437757") or ("5656122") or	US-PGPUB	2002/03/20 10:30
	5	("6156276")).PN. (("4340462") or ("5262029") or ("5437757") or ("5656122") or	USPAT:	2002/03/26 11:01
-	5	("6165276")).PN.	US-PGPUB	
_	3091	(118/715,724,725).CCLS.	USPAT;	2002/03/28 10:30
	0001	(110/110/121/120/12012	US-PGPUB	
-	32	((118/715,724,725).CCLS.) and (clamp same heat\$3 same	USPAT;	2002/03/28 16:06
		(gas with (purge purging backside clean cleaning)))	US-PGPUB	
-	7	5882419.URPN.	USPAT	2002/03/26 11:48
-	14	((118/715,724,725).CCLS.) and (((clean cleaning) with gas)	USPAT;	2002/03/26 13:12
	_	same clamp)	US-PGPUB USPAT;	2002/03/26 13:13
-	0	((118/715,724,725).CCLS.) and ("backside gas" with clean)	US-PGPUB	2002/03/20 13.13
	40	((118/715,724,725).CCLS.) and ("purge gas" with clean)	USPAT:	2002/03/26 13:59
-	18	((116/715,724,725).00L5.) and (purge gas with oldari)	US-PGPUB	2002/00/20 /0/0
	2	((118/715,724,725).CCLS.) and (clamp same "cleaning gas")	USPAT;	2002/03/26 14:02
-	_	((1107110,721,725):00201, 2112 (01211) 22112	US-PGPUB	
_	11	("4146774" "4592924" "4923715" "5000113" "5201990"	USPAT	2002/03/26 14:00
		"5254171" "5366585" "5482749" "5578131" "5616208"		
		"5833854").PN.	1	0000/00/00 1111
-	2	((118/715,724,725).CCLS.) and ("cleaning gas" and ("cl2"	USPAT;	2002/03/26 14:11
	_	"clf3"))	US-PGPUB	2002/03/26 14:08
-	3		USPAT USPAT;	2002/03/26 15:19
-	40	((118/715,724,725).CCLS.) and ("cleaning gas" with (wafer	US-PGPUB	2002/03/20 13.1.
	1467	substrate))	USPAT:	2002/03/26 14:5
•	1467	"purge gas" and clean	US-PGPUB	
_	2	("purge gas" with clean) and "wafer clamp"	USPAT;	2002/03/26 15:18
_	~	(pargo gao mar oroni, and remarks	US-PGPUB	
_	14	"cleaning gas" with "purge gas"	USPAT;	2002/03/26 15:22
			US-PGPUB	
-	345	ries.in.	USPAT;	2002/03/26 15:5
			US-PGPUB USPAT;	2002/03/26 15:5
-	6	ries.in. and wafer	US-PGPUB	2002/03/20 13.3
	7	((118/715,724,725).CCLS.) and (edge with gas with remove)	USPAT;	2002/03/26 16:19
-	,	((116/715,724,725).5025.) and (edge with gas with femoto)	US-PGPUB	
_	5	((118/715,724,725).CCLS.) and (edge with gas with clean)	USPAT;	2002/03/26 16:29
			US-PGPUB	
_	40	((118/715,724,725).CCLS.) and ("backside gas")	USPAT;	2002/03/26 16:3
			US-PGPUB	
-	0	"purge gas" with etch with edge	USPAT;	2002/03/26 16:3
			US-PGPUB	2002/03/26 16:5
-	102	("gas" with etch with edge)	USPAT; US-PGPUB	2002/03/20 10.5
	1	(autotate wafer) with along with addes with das	USPAT;	2002/03/26 16:5
-	22	(substrate wafer) with clean with edges with gas	US-PGPUB	2002/00/20 10:0
	360	((118/715,724,725).CCLS.) and (heat same (susceptor holder	USPAT;	2002/03/26 17:1
-	300	table support)) and (heat same (clamp ring))	US-PGPUB	
_	65		USPAT;	2002/03/26 17:1
		table support)) and (heat same (clamp))	US-PGPUB	
-	193	((118/715,724,725).CCLS.) and (heat with(susceptor holder	USPAT;	2002/03/26 17:2
		table support)) and (heat with (ring clamp))	US-PGPUB	0000/00/00 47.5
-	28	((118/715,724,725).CCLS.) and (heat with(susceptor holder	USPAT;	2002/03/26 17:5
	200	table support)) and (heat with (clamp))	US-PGPUB USPAT;	2002/03/26 17:3
-	800	((118/715,724,725).CCLS.) and (heat with(susceptor holder	US-PGPUB	2002/03/20 17.3
	45	table support)) ((118/715,724,725).CCLS.) and (heat with (clamp))	USPAT;	2002/03/26 18:1
-	45	((110/110,124,120).00L0.) and (neat with (damp))	US-PGPUB	
_	461	118/724,725.ccls. and (heat with wall)	USPAT;	2002/03/26 18:1
-		The state of the s	US-PGPUB	
-	4	("purge gas" or "backside gas") with (effect adj3 deposition)	USPAT;	2002/03/27 14:5
	1		US-PGPUB	

18		ioo T	("purge gas" or "backside gas") with (composition)	USPAT;	2002/03/27 15:48
- 18 "asm" with "epsilon" 0 ("asm" with "epsilon") same purge 1 37897 h01l021\$.ipc. 1 4653 c23c016\$.ipc. 1 653901 h01l021\$.ipc. 2 23c016\$.ipc. 3 38290 c23c016\$.ipc. 1 4 (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition") USPAT: US-PGPUB US		166	("purge gas" or backside gas) with (composition)		2002/00/21 10:10
- 0 ("asm" with "epsilon") same purge		19	"acm" with "ensilon"		2002/03/28 09:56
SPGPUB USPAT; US-PGPUB US-PGPUB US-PAT; US-PGPUB US-PGPUB US-PAT; US-		.0	asin with openion	US-PGPUB	
- 37897 h01l021\$.ipc. US.PGPUB USPAT; US.PGPUB US.PGPU		o	("asm" with "epsilon") same purge		2002/03/28 09:56
- 4653 c23c016\$.ipc.	İ	-			
- 4653 c23c016\$.ipc.		37897	h01l021\$.ipc.		2002/03/28 10:04
- 4653 C23c016\$.ipc.					2002/02/29 10:04
- 653901 h01I021\$.ipc. - 38290 c23c016\$.ipc. 14 (h01I021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed))		4653	c23c016\$.ipc.		2002/03/20 10.04
- 38290 c23c016\$.ipc. 14 (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) 15 (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) 16 (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (composition or compose or composed)) 17 (h01l021\$.ipc. or c23c016\$.ipc.) and ("purge gas" with (porge g					2002/03/28 10:08
- 38290 c23c016\$.ipc.	ĺ	653901	h01l021\$.ipc.		2002/03/20 10:00
14		00000	-22-046¢ inc		2002/03/28 10:08
14	İ	38290	C23CU10\$.ipc.		
Composition or compose or composed)		14	(h01)021\$ inc. or c23c016\$ inc.) and ("purge gas", with		2002/03/28 10:14
25	į.	14		DERWENT	
Comprise\$3))	1	25	(h01l021\$.jpc, or c23c016\$.jpc.) and ("purge gas" with		2002/03/28 10:28
Solution Solution	ĺ			DERWENT	
3091 (118/715,724,725).CCLS. USPAT; US-PGPUB USPAT; US-PGP	!	8			2002/03/28 10:29
Solution Color C					
350 ((118/715,724,725).CCLS.) and (heater with (two second)) USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT	İ	3091	(118/715,724,725).CCLS.		2002/03/28 10:30
33 ((118/715,724,725).CCLS.) and (heater adj.(two second))					2002/02/29 10:22
33		350	((118/715,724,725).CCLS.) and (heater with (two second))		2002/03/20 10.32
- 44 5179677.URPN. ((118/715,724,725).CCLS.) and ((table susceptor support) with heat with mount) ries.in. - 345 ries.in. and (silicon wafer cvd) - 1 ries.in. and ("purge gas" with "composition") - 854 "ti/tin" - 1 "ti/tin" with (results properties) - 1 US-PGPUB USPAT; US-PGPUB US			(44.40/745 704.705) 001.0) and (heater edi (hun eccend))		2002/03/28 12:24
- 44 5179677.URPN. ((118/715,724,725).CCLS.) and ((table susceptor support) with heat with mount) ries.in. - 345 ries.in. and (silicon wafer cvd) - 1 ries.in. and ("purge gas" with "composition") - 854 "ti/tin" - 1 "ti/tin" with (results properties) - 2002/03/28 2002/03		33	((118/715,724,725).CCL5.) and (neater adj (two second))		2002/00/20 12:21
13 ((118/715,724,725).CCLS.) and ((table susceptor support) with heat with mount) ries.in. 26 ries.in. and (silicon wafer cvd) 1 ries.in. and ("purge gas" with "composition") 2002/03/28 USPAT; US-PGPUB U		4.4	5470677 LIDDN		2002/03/28 12:05
heat with mount ries.in.			//////////////////////////////////////		2002/03/28 12:31
- 345 ries.in. 26 ries.in. and (silicon wafer cvd) 1 ries.in. and ("purge gas" with "composition") 2854 "ti/tin" 47 "ti/tin" with (results properties) USPAT; US-PGPUB US		13			
26 ries.in. and (silicon wafer cvd)		345		USPAT;	2002/03/28 12:32
- 1 ries.in. and ("purge gas" with "composition") - 854 "ti/tin" - 854 "ti/tin" - 47 "ti/tin" with (results properties) US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB		0-10			
- 1 ries.in. and ("purge gas" with "composition") - 854 "ti/tin" - 47 "ti/tin" with (results properties) US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT;	,	26	ries.in. and (silicon wafer cvd)		2002/03/28 12:32
- 854 "ti/tin" US-PGPUB USPAT; 2002/03/26					
- 854 "ti/tin" USPAT; 2002/03/26 US-PGPUB USPAT; 2002/03/26 USPAT; 2002/03/26		1	ries.in. and ("purge gas" with "composition")		2002/03/28 12:35
US-PGPUB US-PGPUB USPAT; 2002/03/26					2002/02/20 46:52
uspat; 2002/03/26		854	"ti/tin"	,	2002/03/28 16:53
4/ I/III WIII (ICSUIIS DIODCIIICS)					2002/03/28 17:00
I I I D D D I I I	.	47	"ti/tin" with (results properties)	US-PGPUB	2002/03/20 17:00
0000/00/00		^	Wat /Aim!! with (honofit)		2002/03/28 17:00
- 3 "ti/tin" with (benefit) USPA1; US-PGPUB		3	Turtin with (benefit)		